

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01	100.0	0.26
			<b>Subtotal</b>	<b>0.01</b>	<b>100</b>	<b>0.26</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	0.33	100.0	6.3
			<b>Subtotal</b>	<b>0.33</b>	<b>100</b>	<b>6.3</b>
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0	5.0	0.05
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.03
	Lead alloy	Lead (Pb)	7439-92-1	0.05	92.5	0.93
			<b>Subtotal</b>	<b>0.05</b>	<b>100</b>	<b>1.01</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.21	100.0	4
			<b>Subtotal</b>	<b>0.21</b>	<b>100</b>	<b>4</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03	0.04	0.53
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	1.32
	Copper alloy	Copper (Cu)	7440-50-8	68.68	99.86	1321.85
			<b>Subtotal</b>	<b>68.78</b>	<b>100</b>	<b>1323.7</b>
Mould Compound		Bisphenol-A Bisphenol-A Diglycidyl Ether copolymer	25036-25-3	0.38	1.3	7.31
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.05	7.0	39.38
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	4.09	14.0	78.75
	Filler	Silica fused	60676-86-0	1.75	6.0	33.75
	Carbon Black	Carbon black	1333-86-4	0.12	0.4	2.25
	Filler	Misc. Silica compounds (generic)	14808-60-7	20.46	70.0	393.75
		Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.38	1.3	7.31
			<b>Subtotal</b>	<b>29.23</b>	<b>100</b>	<b>562.5</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.4	100.0	27
			<b>Subtotal</b>	<b>1.4</b>	<b>100</b>	<b>27</b>
			<b>Total</b>	<b>100.01</b>	<b>100</b>	<b>1924.77</b>

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